



PATENT Customer No. 22,852 Attorney Docket No. 04329.2107-03

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re A	Application of:	
Keiichi SASAKI et al.		Group Art Unit: 2823
Application No.: 10/646,703		Examiner: Brewster, William M.
Filed:	August 25, 2003	)
For:	PASTE INCLUDING A MIXTURE OF POWDERS, CONNECTION PLUG, BURYING METHOD, AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD	) ) ) )
	nissioner for Patents Box 1450	

Sir:

Alexandria, VA 22313-1450

## **RESPONSE TO RESTRICTION REQUIREMENT**

In the Office Action dated October 5, 2004, the period for response to which extends through November 5, 2004, the Examiner required restriction under 35 U.S.C. § 121 between the following groups:

Group I, claims 1-3, characterized by the Examiner as drawn to an electrically conductive paste containing metals; and

Group II, claims 5-7, 9-12, and 25-30, characterized by the Examiner as drawn to a method of forming interconnects.

Applicants provisionally elect to prosecute Group II, including claims 5-7, 9-12, and 25-30, without traverse.

Please grant any extensions of time required to enter this response and charge any additional required fees to our deposit account 06-0916.

Respectfully submitted,

FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

Dated: October 29, 2004

Qingyu Yin

\*With limited recognition under 37 C.F.R. § 10.9(b)